#### PATENT APPLICATION

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Toshiyuki OGATA, et al.

Appln. No.: NOT YET ASSIGNED

Confirmation No.: NOT YET ASSIGNED Group Art Unit: NOT YET ASSIGNED

Filed: August 07, 2001 Examiner: NOT YET ASSIGNED

For: POSITIVE RESIST COMPOSITION AND BASE MATERIAL CARRYING LAYER OF

THE POSITIVE RESIST COMPOSITION

#### PRELIMINARY AMENDMENT

Commissioner for Patents Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

#### **IN THE CLAIMS:**

### Please enter the following amended claims:

10. A base material comprising:

an organic polymer layer as a first layer formed on a substrate; and

a second resist layer formed on said organic polymer layer, said second resist layer being composed of a positive resist composition according to claim 1 and having a thickness of from 50 to 200 nm.

# AMENDMENT Attorney Docket No. Q65755

## **REMARKS**

Entry and consideration of this Amendment is respectfully requested.

Respectfully submitted,

Registration No. 21,092

SUGHRUE, MION, ZINN, MACPEAK & SEAS, PLLC 2100 Pennsylvania Avenue, N.W. Washington, D.C. 20037-3213 Telephone: (202) 293-7060

Facsimile: (202) 293-7860

RJS/ob

Date: August 7, 2001

AMENDMENT Attorney Docket No. Q65755

# APPENDIX VERSION WITH MARKINGS TO SHOW CHANGES MADE

# **IN THE CLAIMS:**

## The claims are amended as follows:

10. A base material comprising:

an organic polymer layer as a first layer formed on a substrate; and a second resist layer formed on said organic polymer layer, said second resist layer being composed of a positive resist composition according to any one of claims 1 to 9 claim 1 and having a thickness of from 50 to 200 nm.